

AMENDMENTS TO THE CLAIMS

1. (Original) A method of manufacturing a lapping plate comprising:
selectively etching a metal plate; and
imbedding diamond particles into said metal plate.
2. (Original) The method of claim 1 wherein said etching step includes:
applying a photoresist layer to said metal plate; and
selectively removing photoresist from a surface of said metal plate.
3. (Previously Presented) A method of manufacturing a lapping plate comprising:
applying a photoresist layer to a metal plate;
selectively exposing areas of said photoresist layer to electromagnetic radiation;
developing said photoresist layer;
etching areas of said metal plate; and
imbedding diamond particles into non-etched areas of said metal plate.
4. (Original) The method of claim 3 wherein said selectively exposing operating includes:
providing a mask between an electromagnetic radiation source and said photoresist layer;
5. (Original) The method of claim 4 wherein said mask is a wire mesh.

6. (Original) The method of claim 4 wherein said electromagnetic radiation is ultra-violet radiation.
7. (Original) The method of claim 4 wherein said photoresist is a positive photoresist.
8. (Original) The method of claim 4 wherein said photoresist is a negative photoresist.
9. (Original) The method of claim 4 wherein said etching operation is a wet-etch operation.
10. (Original) The method of claim 4 wherein said diamond particles have a diameter less than 50 nanometers.
11. (Previously Presented) A method of fabricating a read/write head for a disk drive, comprising:
 - applying a photoresist layer to a metal plate;
 - selectively exposing areas of said photoresist layer to electromagnetic radiation;
 - developing said photoresist layer;
 - etching areas of said metal plate;
 - imbedding diamond particles into non-etched areas of said metal disk to create a lapping plate; and
 - lapping a read/write head with said lapping plate.

12. (Original) The method of claim 11 wherein said selectively exposing operating includes:
providing a mask between an electromagnetic radiation source and said photoresist layer;
13. (Original) The method of claim 12 wherein said mask is a wire mesh.
14. (Original) The method of claim 12 wherein said electromagnetic radiation is ultra-violet radiation.
15. (Original) The method of claim 12 wherein said photoresist is a positive photoresist.
16. (Original) The method of claim 12 wherein said photoresist is a negative photoresist.
17. (Original) The method of claim 12 wherein said etching operation is a wet-etch operation.
18. (Original) The method of claim 12 wherein said diamond particles have a diameter less than 50 nanometers.
19. (Original) The method of claim 18 wherein said read/write head is a GMR read/write head.

20. (Original) The method of claim 18 wherein a pole tip recession for said GMR read/write head is between 2 and 3 nanometers.

21. (Withdrawn) A lapping plate comprising:
a metal plate including a plurality of etched areas, said etched areas formed from an etching operation through a developed photoresist mask; and
diamond particles imbedded into non-etched areas of the metal plate.

22. (Withdrawn) The lapping plate of claim 21 wherein said photoresist is a positive photoresist.

23. (Withdrawn) The lapping plate of claim 21 wherein said photoresist is a negative photoresist.

24. (Withdrawn) The lapping plate of claim 21 wherein said metal plate is wet-etched.

25. (Withdrawn) The lapping plate of claim 21 wherein said diamond particles have a diameter less than 50 nanometers.